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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	128300
Number of Logic Elements/Cells	340000
Total RAM Bits	19456000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma3k3f40c4n

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Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed	Core Speed Grade										
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I3YY	14			
3 GX channel—8.5 Gbps	_	Yes	Yes	Yes	_	Yes	Yes <sup>(4)</sup>	Yes			

#### Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.
- (3) C2L, I2L, and I3L speed grades are for low-power devices.
- (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transacius Crad Crado	Core Speed Grade								
Transceiver Speed Grade	C1	C2	12	13					
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_					
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes					

#### Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.

## **Absolute Maximum Ratings**

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V <sub>CC</sub>	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V <sub>CCPT</sub>	Power supply for programmable power technology	-0.5	1.8	V
V <sub>CCPGM</sub>	Power supply for configuration pins	-0.5	3.9	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V <sub>CCBAT</sub>	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V <sub>CCPD</sub>	I/O pre-driver power supply	-0.5	3.9	V
V <sub>CCIO</sub>	I/O power supply	-0.5	3.9	V

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Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V <sub>CCD_FPLL</sub>	PLL digital power supply	-0.5	1.8	V
V <sub>CCA_FPLL</sub>	PLL analog power supply	-0.5	3.4	V
V <sub>I</sub>	DC input voltage	-0.5	3.8	V
T <sub>J</sub>	Operating junction temperature	-55	125	°C
T <sub>STG</sub>	Storage temperature (No bias)	-65	150	°C
I <sub>OUT</sub>	DC output current per pin	-25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V <sub>CCT_GXBL</sub>	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

## **Maximum Allowed Overshoot and Undershoot Voltage**

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

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Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min <sup>(4)</sup>	Тур	Max <sup>(4)</sup>	Unit
t <sub>RAMP</sub> Pov	Power supply ramp time	Standard POR	200 μs	_	100 ms	_
	Power supply rainp time	Fast POR	200 μs	_	4 ms	_

#### Notes to Table 6:

- (1)  $V_{CCPD}$  must be 2.5 V when  $V_{CCIO}$  is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V.  $V_{CCPD}$  must be 3.0 V when  $V_{CCIO}$  is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V<sub>CCBAT</sub> to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V<sub>CCBAT</sub>. Stratix V devices will not exit POR if V<sub>CCBAT</sub> stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit	
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V	
(1), (3)	side)	७४, ७७, ७१	2.375	2.5	2.625	V	
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V	
$(1), (\overline{3})$	side)	রম, রহ	2.375	2.5	2.625	V	
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V	
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
			0.82	0.85	0.88	V	
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93		
(2)	Treceiver arialog power supply (left side)	un, us, ui	0.97	1.0	1.03		
			1.03	1.05	1.07		

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Table 8 shows the transceiver power supply voltage requirements for various conditions.

**Table 8. Transceiver Power Supply Voltage Requirements** 

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB (2)	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:		4.05			
■ Data rate > 10.3 Gbps.	All	1.05			
■ DFE is used.					
If ANY of the following conditions are true <sup>(1)</sup> :			3.0		
ATX PLL is used.					
■ Data rate > 6.5Gbps.	All	1.0			
■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.				1.5	V
If ALL of the following	C1, C2, I2, and I3YY	0.90	2.5		
conditions are true:  ATX PLL is not used.					
■ Data rate ≤ 6.5Gbps.	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		
DFE, AEQ, and EyeQ are not used.					

#### Notes to Table 8:

- (1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.
- (2) If the VCCR\_GXB and VCCT\_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR\_GXB and VCCT\_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

### **DC Characteristics**

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

### **Supply Current**

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

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Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices

I/O Standard		V <sub>CCIO</sub> (V)			V <sub>REF</sub> (V)			V <sub>TT</sub> (V)	
I/O Standard	Min	Тур	Max	Min	Тур	Max	Min	Тур	Мах
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	V <sub>REF</sub> – 0.04	$V_{REF}$	V <sub>REF</sub> + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V <sub>REF</sub> – 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V <sub>CCIO</sub> /2	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	_	V <sub>CCIO</sub> /2	_
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.53 * V <sub>CCIO</sub>	_	V <sub>CCIO</sub> /2	_
HSUL-12	1.14	1.2	1.3	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	_	_	_

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)

I/O Standard	V <sub>IL(D(</sub>	<sub>c)</sub> (V)	V <sub>IH(D</sub>	<sub>C)</sub> (V)	V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I (mA)	l <sub>oh</sub>
i/U Stanuaru	Min	Max	Min Max		Max Min		Max	Min	I <sub>ol</sub> (mA)	(mA)
SSTL-2 Class I	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.608	V <sub>TT</sub> + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.81	V <sub>TT</sub> + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	V <sub>TT</sub> – 0.603	V <sub>TT</sub> + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	0.28	V <sub>CCIO</sub> - 0.28	13.4	-13.4
SSTL-15 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	8	-8
SSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	16	-16
SSTL-135 Class I, II	_	V <sub>REF</sub> – 0.09	V <sub>REF</sub> + 0.09	_	V <sub>REF</sub> – 0.16	V <sub>REF</sub> + 0.16	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_
SSTL-125 Class I, II	_	V <sub>REF</sub> – 0.85	V <sub>REF</sub> + 0.85	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_
SSTL-12 Class I, II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_

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Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

I/O	V <sub>CCIO</sub> (V)			V <sub>DIF(I</sub>	<sub>DC)</sub> (V)		V <sub>X(AC)</sub> (V)		V <sub>CM(DC)</sub> (V)			V <sub>DIF(AC)</sub> (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V <sub>CCIO</sub> + 0.3	_	0.5* V <sub>CCIO</sub>	_	0.4* V <sub>CCIO</sub>	0.5* V <sub>CCIO</sub>	0.6* V <sub>CCIO</sub>	0.3	V <sub>CCIO</sub> + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V <sub>CCIO</sub> - 0.12	0.5* V <sub>CCIO</sub>	0.5*V <sub>CCIO</sub> + 0.12	0.4* V <sub>CCIO</sub>	0.5* V <sub>CCIO</sub>	0.6* V <sub>CCIO</sub>	0.44	0.44

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	<sub>CIO</sub> (V)	(10)		$V_{ID} (mV)^{(8)}$ $V_{ICM(DC)} (V)$			Vo	D (V) (	6)	V	<sub>OCM</sub> (V)	(6)		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Trar	nsmitte						of the high-s I/O pin speci							. For
2.5 V	2.375	2.5	2.625	100	V <sub>CM</sub> =	_	0.05	D <sub>MAX</sub> ≤ 700 Mbps	1.8	0.247		0.6	1.125	1.25	1.375
LVDS (1)	2.373	2.3	2.023	100	1.25 V		1.05	D <sub>MAX</sub> > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_		_
RSDS (HIO) <sup>(2)</sup>	2.375	2.5	2.625	100	V <sub>CM</sub> = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) (3)	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_	_	0.6	D <sub>MAX</sub> ≤ 700 Mbps	1.8	_	_	_	_	_	_
), (9)	_	_	_	300	_	_	1	D <sub>MAX</sub> > 700 Mbps	1.6	_	_	_	_	_	_

#### Notes to Table 22:

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed  $V_{\text{ICM}}$ ,  $V_{\text{OD}}$ , and  $V_{\text{OCM}}$  specifications for BLVDS. They depend on the system topology.
- (6) RL range:  $90 \le RL \le 110 \Omega$ .
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5  $\rm V.$

## **Power Consumption**

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus<sup>®</sup> II PowerPlay Power Analyzer feature.

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> <sup>(5)</sup>	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	_	-0.4		_	-0.4	_		-0.4	_	1	V
Peak-to-peak differential input voltage	_	200	_	1600	200		1600	200	_	1600	mV
V <sub>ICM</sub> (AC coupled) (3)	Dedicated reference clock pin	1050/	1000/90	00/850 <sup>(2)</sup>	1050/	1000/90	00/850 <sup>(2)</sup>	1050/	1050/1000/900/850 (2)		mV
coupled) (9	RX reference clock pin	1.0/0.9/0.85 (4)			1.	0/0.9/0	.85 <sup>(4)</sup>	1.	0/0.9/0	.85 <sup>(4)</sup>	V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) <sup>(20)</sup>	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120	_	_	-120	_	_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R <sub>REF</sub> (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_			_	
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 4 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	85– $\Omega$ setting	_	85 ± 30%	_	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-	100–Ω setting	_	100 ± 30%		_	100 ± 30%	_	_	100 ± 30%	_	Ω
chip termination resistors <sup>(21)</sup>	120–Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	_	150 ± 30%	_	Ω
	V <sub>CCR_GXB</sub> = 0.85 V or 0.9 V full bandwidth	_	600	_	_	600	_	_	600	_	mV
V <sub>ICM</sub> (AC and DC	V <sub>CCR_GXB</sub> = 0.85 V or 0.9 V half bandwidth	_	600	_	_	600	_	_	600	_	mV
coupled)	$V_{CCR\_GXB} = \\ 1.0 \text{ V/1.05 V} \\ \text{full} \\ \text{bandwidth}$	_	700	_	_	700	_	_	700	_	mV
	V <sub>CCR_GXB</sub> = 1.0 V half bandwidth	_	750	_	_	750	_	_	750	_	mV
t <sub>LTR</sub> (11)	_	_	_	10	_	_	10	_	_	10	μs
t <sub>LTD</sub> (12)	_	4	_		4			4			μs
t <sub>LTD_manual</sub> (13)	_	4	_		4			4			μs
t <sub>LTR_LTD_manual</sub> (14)		15			15		_	15	_		μs
Run Length		_	_	200	_		200	_	-	200	UI
Programmable equalization (AC Gain) (10)	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	_	_	16	_	_	16	_	_	16	dB

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0	_	0	_	_	0	_	_	0	_	dB
	DC Gain Setting = 1	_	2	_	_	2	_	_	2	_	dB
Programmable DC gain	DC Gain Setting = 2		4	_	_	4		_	4	_	dB
	DC Gain Setting = 3		6		_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8		_	8		_	8	_	dB
Transmitter											
Supported I/O Standards	_		1.4-V and 1.5-V PCML								
Data rate (Standard PCS)	_	600	_	12200	600		12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
	85-Ω setting	_	85 ± 20%	_	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-	100-Ω setting		100 ± 20%	_	_	100 ± 20%		_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150-Ω setting	_	150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V <sub>OCM</sub> (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V <sub>OCM</sub> (DC coupled)	_	_	650	_	_	650	_	_	650	_	mV
Rise time (7)	20% to 80%	30	_	160	30	_	160	30		160	ps
Fall time <sup>(7)</sup>	80% to 20%	30	_	160	30		160	30	_	160	ps
Intra-differential pair skew	Tx V <sub>CM</sub> = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	_	_	120	_	_	120	_	_	120	ps

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Figure 2 shows the differential transmitter output waveform.

Figure 2. Differential Transmitter Output Waveform

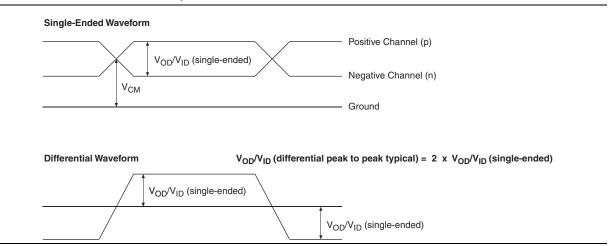


Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)



Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23.

Table 28 lists the Stratix V GT transceiver specifications.

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 4 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY	C4,I4			II-ni4
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)	_	(8)	(6)	_	(8)	(6)	_	(8)	Mbps
f <sub>HSDR</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)	_	(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)		(7)	Mbps
DPA Mode														
DPA run length	_	_	_	1000 0	_		1000 0	_	_	1000 0	_	_	1000 0	UI
Soft CDR mod	e													
Soft-CDR PPM tolerance	_	_	_	300	_	_	300	_	_	300	_	_	300	± PPM
Non DPA Mode	е													
Sampling Window	_	_		300			300	_		300	_	_	300	ps

#### Notes to Table 36:

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F<sub>MAX</sub> specification is based on the fast clock used for serial data. The interface F<sub>MAX</sub> is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

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Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 2 of 2)

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

#### Notes to Table 40:

- (1) The typical value equals the average of the minimum and maximum values.
- (2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t<sub>DQS\_PSERR</sub>) for Stratix V Devices (1)

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

#### Notes to Table 41:

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 1 of 2) (2), (3)

Clock Network	Parameter	Symbol	C	C1 C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit	
NEIWUIK			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t <sub>JIT(per)</sub>	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	t <sub>JIT(cc)</sub>	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t <sub>JIT(per)</sub>	-75	75	<del>-</del> 75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	t <sub>JIT(cc)</sub>	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	t <sub>JIT(duty)</sub>	<del>-</del> 75	75	-75	75	-90	90	-90	90	ps

<sup>(1)</sup> This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a −2 speed grade is ±78 ps or ±39 ps.

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Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)
Stratix V E (1)	5SEE9	_	342,742,976	700,888
Stratix V L 17	5SEEB	_	342,742,976	700,888

#### Notes to Table 47:

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Banker		Active Serial (1)	)	Fas	t Passive Parall	el <sup>(2)</sup>
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)  100 100 100 100 100 100 100 100 100 1	Min Config Time (s)
	A3	4	100	0.534	32	100	0.067
	AS	4	100	0.344	32	100	0.043
	A4	4	100	0.534	32	100	0.067
	A5	4	100	0.675	32	100	0.084
	A7	4	100	0.675	32	100	0.084
GX	A9	4	100	0.857	32	100	0.107
	AB	4	100	0.857	32	100	0.107
	B5	4	100	0.676	32	100	0.085
	B6	4	100	0.676	32	100	0.085
	В9	4	100	0.857	32	100	0.107
	BB	4	100	0.857	32	100	0.107
GT	C5	4	100	0.675	32	100	0.084
G1	C7	4	100	0.675	32	100	0.084

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Table 49. DCLK-to-DATA[] Ratio (1) (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
1FF ×32	Enabled	Disabled	8
	Enabled	Enabled	8

#### Note to Table 49:

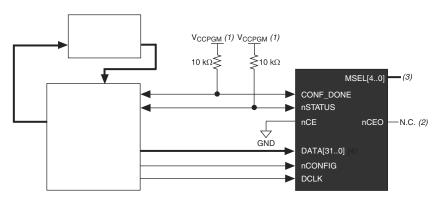
(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio -1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



#### Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V<sub>CCPGM</sub> must be high enough to meet the V<sub>IH</sub> specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V<sub>CCPGM</sub>.
- (2) You can leave the nceo pin unconnected or use it as a user I/O pin when it does not feed another device's nce pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP  $\times 8$ , use DATA [7..0]. If you use FPP  $\times 16$ , use DATA [15..0].

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1  $^{(1)}$ 

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nconfig low to conf_done low	_	600	ns
t <sub>CF2ST0</sub>	nconfig low to nstatus low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(2)</sup>	μS
t <sub>CF2ST1</sub>	nconfig high to nstatus high	_	1,506 <sup>(2)</sup>	μS
t <sub>CF2CK</sub> (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t <sub>ST2CK</sub> (5)	nstatus high to first rising edge of DCLK	2	_	μS
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	N-1/f <sub>DCLK</sub> <sup>(5)</sup>	_	S
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f <sub>MAX</sub>	DCLK frequency (FPP ×32)	_	100	MHz
t <sub>R</sub>	Input rise time	_	40	ns
t <sub>F</sub>	Input fall time	_	40	ns
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum  DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	t <sub>CD2CU</sub> + (8576 × CLKUSR period) <sup>(4)</sup>	_	_

#### Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.
- (6) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

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## **Active Serial Configuration Timing**

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52. DCLK Frequency Specification in the AS Configuration Scheme (1), (2)

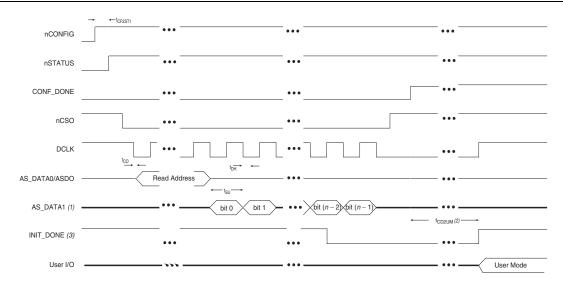
Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

#### Notes to Table 52:

- (1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

Figure 14. AS Configuration Timing



### Notes to Figure 14:

- (1) If you are using AS ×4 mode, this signal represents the AS\_DATA [3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or  ${\tt CLKUSR}$  pin.
- (3) After the option bit to enable the  $INIT_DONE$  pin is configured into the device, the  $INIT_DONE$  goes low.

Table 53 lists the timing parameters for AS  $\times 1$  and AS  $\times 4$  configurations in Stratix V devices.

Table 53. AS Timing Parameters for AS  $\times$ 1 and AS  $\times$ 4 Configurations in Stratix V Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CO</sub>	DCLK falling edge to AS_DATAO/ASDO output	_	2	ns
t <sub>SU</sub>	Data setup time before falling edge on DCLK	1.5	_	ns
t <sub>H</sub>	Data hold time after falling edge on DCLK	0	_	ns

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Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nCONFIG low to CONF_DONE low	_	600	ns
t <sub>CF2ST0</sub>	nCONFIG low to nSTATUS low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	<del></del>	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(1)</sup>	μS
t <sub>CF2ST1</sub>	nCONFIG high to nSTATUS high	_	1,506 <sup>(2)</sup>	μS
t <sub>CF2CK</sub> (5)	nCONFIG high to first rising edge on DCLK	1,506	<del></del>	μS
t <sub>ST2CK</sub> (5)	nstatus high to first rising edge of DCLK	2	_	μS
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	0	_	ns
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f <sub>MAX</sub>	DCLK frequency	_	125	MHz
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μ\$
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum  DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	$t_{\text{CD2CU}}$ + (8576 × CLKUSR period) $^{(4)}$	_	_

#### Notes to Table 54:

- (1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.
- (5) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

## Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximum Frequency

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles <sup>(1)</sup>
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP (2)	125 MHz	8576
DCLK	PS, FPP	125 MHz	

#### Notes to Table 55:

- $(1) \quad \text{The minimum number of clock cycles required for device initialization}.$
- (2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.

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Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions	
G			
Н	_	<del>-</del>	
1			
J	J TAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus).  JTAG Timing Specifications:  TMS  TDI  TCK  TJPSU  TJ	
K L M N	_		
P	PLL Specifications	Diagram of PLL Specifications (1)  CLKOUT Pins  Four Core Clock  Reconfigurable in User Mode  External Feedback  Note:  (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.	
Q	_	——————————————————————————————————————	
R	R <sub>L</sub>	Receiver differential input discrete resistor (external to the Stratix V device).	
		1.000.10.1 distribution input distribution fortisting to the official v device).	

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## Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions	
	V <sub>CM(DC)</sub>	DC common mode input voltage.	
	V <sub>ICM</sub>	Input common mode voltage—The common mode of the differential signal at the receiver.	
	V <sub>ID</sub>	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.	
	V <sub>DIF(AC)</sub>	AC differential input voltage—Minimum AC input differential voltage required for switching.	
	V <sub>DIF(DC)</sub>	DC differential input voltage— Minimum DC input differential voltage required for switching.	
	V <sub>IH</sub>	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.	
	V <sub>IH(AC)</sub>	High-level AC input voltage	
	V <sub>IH(DC)</sub>	High-level DC input voltage	
V	<b>V</b> <sub>IL</sub>	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.	
	V <sub>IL(AC)</sub>	Low-level AC input voltage	
	V <sub>IL(DC)</sub>	Low-level DC input voltage	
	V <sub>OCM</sub>	Output common mode voltage—The common mode of the differential signal at the transmitter.	
	<b>V</b> <sub>OD</sub>	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.	
	V <sub>SWING</sub>	Differential input voltage	
	V <sub>X</sub>	Input differential cross point voltage	
	V <sub>OX</sub>	Output differential cross point voltage	
W	W	High-speed I/O block—clock boost factor	
Χ			
Υ		_	
Z			

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